



RoHS COMPLIANT

- 1 Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] per IPC 4101/21, gold surface finish.
- 2 Substrate: 3.18mm \pm 0.18mm [0.125" \pm 0.007"] FR4/G10 or equivalent high temp material. Non-clad.
- 3 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.).
- 4 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.). Contact material- BeCu; finish 0.25 μ m [10 μ "] Au over 2.54 μ m [100 μ "] Ni (min.).
- 5 Test points: material- Phosphor Bronze; plating- Sn over 1.27 μ m [50 μ "] Ni. Gold flash on contact end.

Description: Carrier Adaptor (CA)
 32 position QFP ZIF socket (mini-grid on 0.040" centers)
 to 32 position QFP surface-mountable leadless foot with test points.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

CA-QFE32SA-L-Z-T-02F Drawing	Status: Released	Scale: 1.5:1	Rev: A
<p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: H. Hansen		Date: 1/8/06
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